

ABSTRACT

The present invention provides a resin plating method using an etching bath containing manganese as an active
5 ingredient, the method being capable of maintaining stable etching performance even during continuous use. The resin plating method includes: an etching step, which uses a resin material-containing article as an object to be treated and etches the article using an acidic etching bath containing manganese; a
10 catalyst application step, which uses palladium as a catalyst metal; and an electroless plating step; and the method further includes a step of maintaining the palladium concentration in the acidic etching bath at 100 mg/L or less.